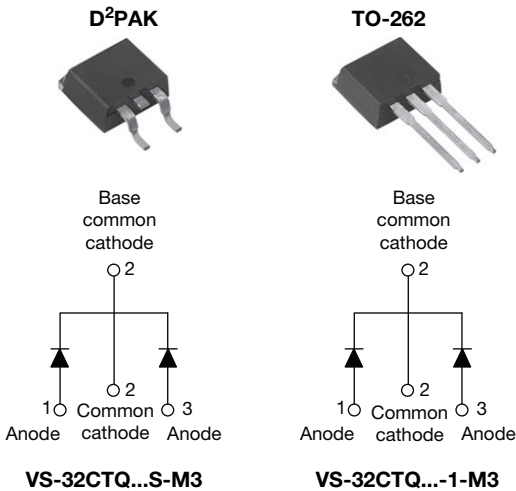


High Performance Schottky Rectifier, 2 x 15 A



FEATURES

- 150 °C T_J operation
- Low forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified meets JESD 201 class 1A whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

DESCRIPTION

The VS-32CTQ... Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 150 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

PRODUCT SUMMARY

I _{F(AV)}	2 x 15 A
V _R	25 V, 30 V
V _F at I _F	0.40 V
I _{RM} typ.	97 mA at 125 °C
T _J max.	150 °C
E _{AS}	13 mJ
Package	TO-263AB (D ² PAK), TO-262AA
Diode variation	Common cathode

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
I _{F(AV)}	Rectangular waveform	30	A
V _R RRM		25, 30	V
I _{FSM}	t _p = 5 μs sine	900	A
V _F	15 A _{pk} , T _J = 125 °C	0.40	V
T _J	Range	-55 to +150	°C

VOLTAGE RATINGS

PARAMETER	SYMBOL	VS-32CTQ025SHM3 VS-32CTQ025-1HM3	VS-32CTQ030SHM3 VS-32CTQ030-1HM3	UNITS
Maximum DC reverse voltage	V _R	25	30	V
Maximum working peak reverse voltage	V _{RWM}			



ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current See fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 115\text{ }^\circ\text{C}$, rectangular waveform		30	A
Maximum peak one cycle non-repetitive surge current See fig. 7	I_{FSM}	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with rated V_{RRM} applied	900	
		10 ms sine or 6 ms rect. pulse		250	
Non-repetitive avalanche energy	E_{AS}	$T_J = 25\text{ }^\circ\text{C}$, $I_{AS} = 1.20\text{ A}$, $L = 11.10\text{ mH}$		13	mJ
Repetitive avalanche current	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical		3	A

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop See fig. 1	$V_{FM}^{(1)}$	15 A	$T_J = 25\text{ }^\circ\text{C}$	0.49	V
		30 A		0.58	
		15 A	$T_J = 125\text{ }^\circ\text{C}$	0.40	
		30 A		0.53	
Maximum reverse leakage current	$I_{RM}^{(1)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{rated } V_R$	1.75	mA
		$T_J = 125\text{ }^\circ\text{C}$		145	
Typical reverse leakage current	$I_{RM}^{(1)}$	$T_J = 125\text{ }^\circ\text{C}$	$V_R = \text{rated } V_R$	97	mA
Threshold voltage	$V_{F(TO)}$	$T_J = T_J$ maximum		0.233	V
Forward slope resistance	r_t			9.09	$\text{m}\Omega$
Maximum junction capacitance per leg	C_T	$V_R = 5\text{ V}_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^\circ\text{C}$		1300	pF
Typical series inductance per leg	L_S	Measured lead to lead 5 mm from package body		8.0	nH
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	$\text{V}/\mu\text{s}$

Note

⁽¹⁾ Pulse width < 300 μs , duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}			-55 to +150	$^\circ\text{C}$
Maximum thermal resistance, junction to case per leg	R_{thJC}	DC operation See fig. 4		3.25	$^\circ\text{C}/\text{W}$
Typical thermal resistance, case to heatsink	R_{thCS}	Mounting surface, smooth and greased		0.50	
Approximate weight				2	g
				0.07	oz.
Mounting torque	minimum			6 (5)	$\text{kgf} \cdot \text{cm}$ $(\text{lbf} \cdot \text{in})$
	maximum			12 (10)	
Marking device		Case style TO-263AB (D ² PAK)		32CTQ025SH	
				32CTQ030SH	
		Case style TO-262AA		32CTQ025-1H	
				32CTQ030-1H	

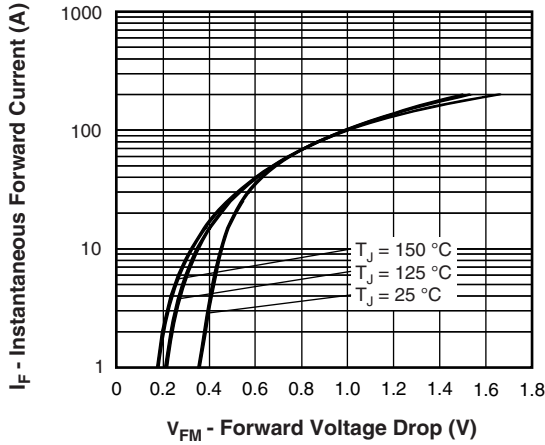


Fig. 1 - Maximum Forward Voltage Drop Characteristics

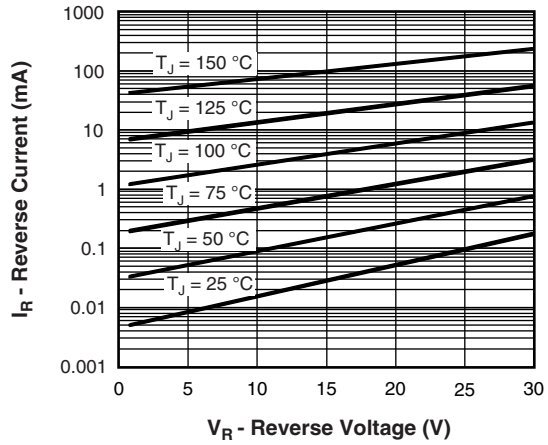


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

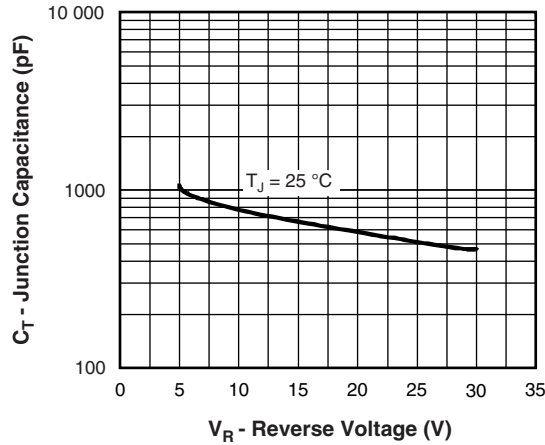


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

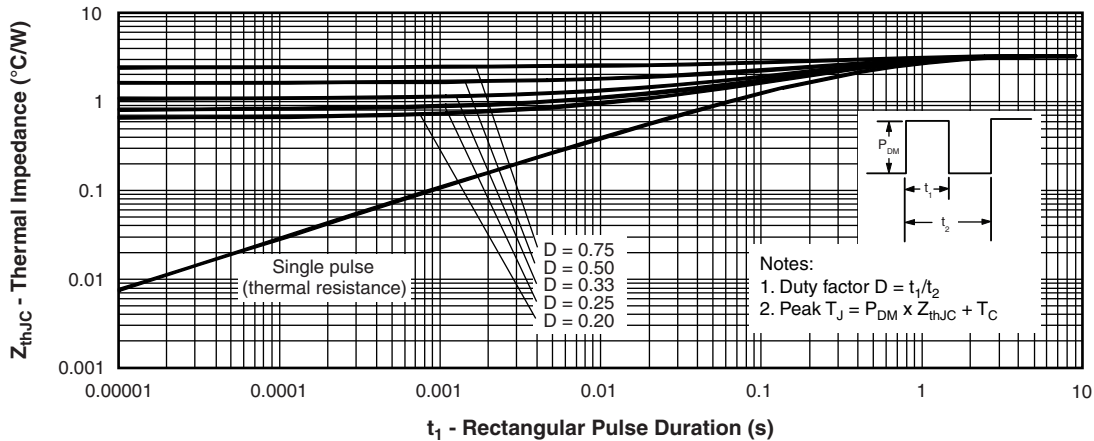


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

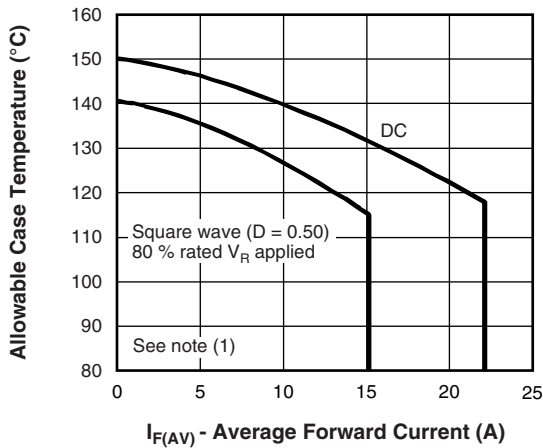


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

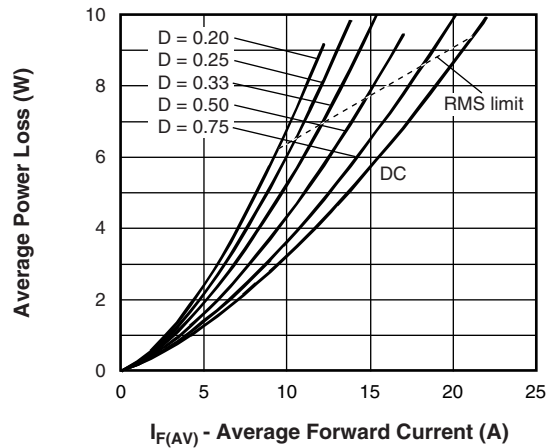


Fig. 6 - Forward Power Loss Characteristics

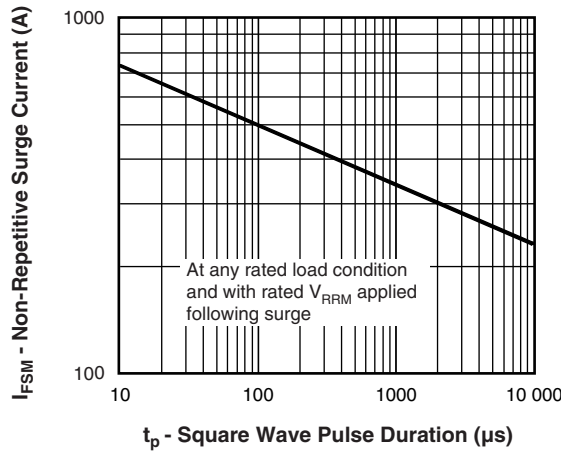


Fig. 7 - Maximum Non-Repetitive Surge Current

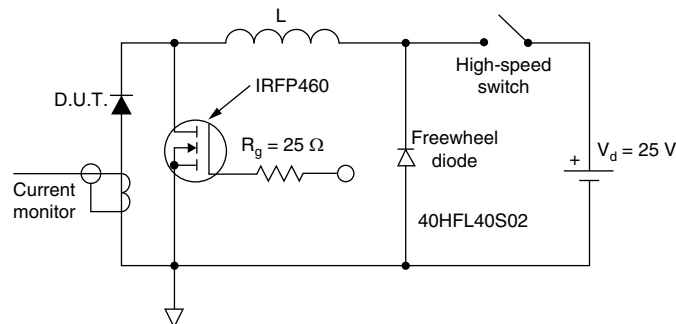


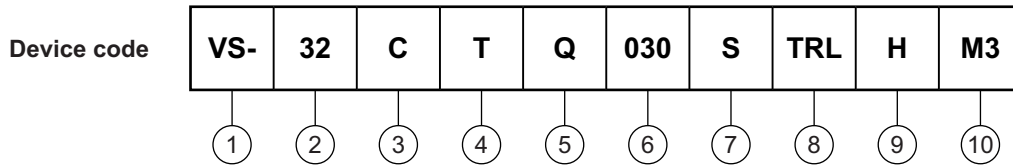
Fig. 8 - Unclamped Inductive Test Circuit

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 $P_{d_{REV}}$ = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (30 A)
- 3** - Circuit configuration: C = common cathode
- 4** - T = TO-220
- 5** - Schottky "Q" series
- 6** - Voltage ratings ———

025 = 25 V
030 = 30 V
- 7** -
 - S = D²PAK
 - -1 = TO-262
- 8** -
 - None = tube
 - TRL = tape and reel (left oriented - for D²PAK only)
 - TRR = tape and reel (right oriented - for D²PAK only)
- 9** - H = AEC-Q101 qualified
- 10** - M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-32CTQ025SHM3	50	1000	Antistatic plastic tubes
VS-32CTQ025STRRH3	800	800	13" diameter reel
VS-32CTQ025STRLH3	800	800	13" diameter reel
VS-32CTQ025-1HM3	50	1000	Antistatic plastic tubes
VS-32CTQ030SHM3	50	1000	Antistatic plastic tubes
VS-32CTQ030STRRH3	800	800	13" diameter reel
VS-32CTQ030STRLH3	800	800	13" diameter reel
VS-32CTQ030-1HM3	50	1000	Antistatic plastic tubes

LINKS TO RELATED DOCUMENTS		
Dimensions	TO-263AB (D ² PAK)	www.vishay.com/doc?95046
Dimensions	TO-262AA	www.vishay.com/doc?95419
Part marking information	TO-263AB (D ² PAK)	www.vishay.com/doc?95444
Part marking information	TO-262AA	www.vishay.com/doc?95443
Packaging information		www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010		E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039		E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070		H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4	L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029		L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4	L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065		L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2	L4	4.78	5.28	0.188	0.208	

Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB

TO-262

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262



$\oplus 0.010 \text{ M} \text{ A} \text{ M} \text{ B}$



Lead assignments

- Diodes**
 1. - Anode (two die)/open (one die)
 2., 4. - Cathode
 3. - Anode



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



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